

TO-B0603BY-BWE-5

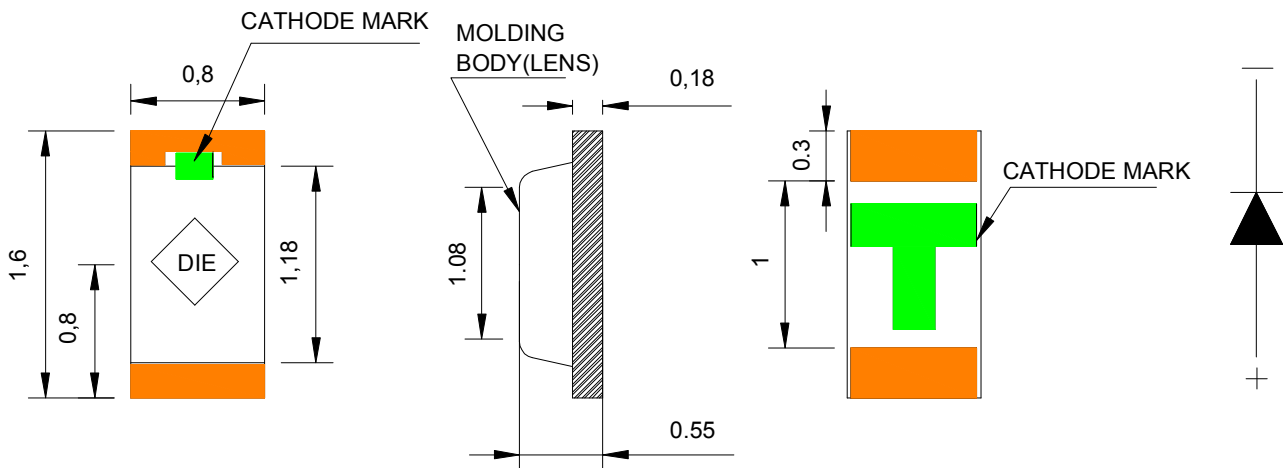
Surface Mount Device LED

Part Number	Chip		Lens Color
	Material	Source Color	
TO-B0603BY-BWE-5	InGaN	Ultra White	Yellow Diffused

Features

- IC compatible
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow solder process
- Top view type
- Package in 8 mm tape on 7" diameter reel
- RoHS compliant
- Moisture sensitivity level: level 3

Dimensions



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm unless otherwise noted.

Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating	Unit
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	mA
Power Dissipation	105	mW
Continuous Forward Current	25	mA
Reverse Voltage	5	V
Operating Temperature Range	-55°C to +85°C	
Storage Temperature Range	-55°C to +105°C	
IR Reflow Soldering Profile For Lead Free Soldering	260°C	

Electrical / Optical Characteristic @ Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I _v	86		258	mcd	I _F =5mA
Viewing Angle	2θ _{1/2}		130		deg	I _F =5mA
Forward Voltage	V _F		3.0		V	I _F =5mA
Reverse Current	I _R			10	μA	V _R =5V
Color Temperature	T _c		/		K	I _F =5mA
Chromaticity Coordinates	X		0.23			I _F =5mA
Chromaticity Coordinates	Y		0.20			I _F =5mA

Bin Code List for Reference

Luminous Intensity		Unit : mcd@5mA
Bin Code	Min	Max
86-103	86	103
103-124	103	124
124-149	124	149
149-179	149	179
179-215	179	215
215-258	215	258

Tolerance of Luminous Intensity on each bin is $\pm 15\%$

Forward Voltage		Unit : mcd@5mA
Bin Code	Min	Max
V0	2.6	2.8
V1	2.8	3.0
V2	3.0	3.2
V3	3.2	3.4

Tolerance of Forward Voltage on each bin is $\pm 0.1V$

Color Bins

BW1					
X	0.217	0.228	0.21	0.199	0.217
Y	0.146	0.164	0.2	0.182	0.146
BW2					
X	0.228	0.239	0.221	0.21	0.228
Y	0.164	0.182	0.218	0.2	0.164
BW3					
X	0.239	0.25	0.232	0.221	0.239
Y	0.182	0.2	0.236	0.218	0.182
BW4					
X	0.25	0.261	0.243	0.232	0.25
Y	0.2	0.218	0.254	0.236	0.2

